### 3.3 V Zero Delay Clock Buffer

## NB2304A

The NB2304A is a versatile, 3.3 V zero delay buffer designed to distribute high-speed clocks in PC, workstation, datacom, telecom and other high-performance applications. It is available in an 8 pin package. The part has an on-chip PLL which locks to an input clock presented on the REF pin. The PLL feedback is required to be driven to FBK pin, and can be obtained from one of the outputs. The input-to-output propagation delay is guaranteed to be less than 250 ps , and the output-to-output skew is guaranteed to be less than 200 ps.

The NB2304A has two Banks of two outputs each. Multiple NB2304A devices can accept the same input clock and distribute it. In this case, the skew between the outputs of the two devices is guaranteed to be less than 500 ps .

The NB2304A is available in two different configurations (Refer to NB2304A Configurations Table). The NB2304AI1 is the base part, where the output frequencies equal the reference if there is no counter in the feedback path. The NB2304AI2 allows the user to obtain REF, $1 / 2 \mathrm{X}$ and 2 X frequencies on each output Bank. The exact configuration and output frequencies depend on which output drives the feedback pin.

## Features

- Zero Input - Output Propagation Delay, Adjustable by Capacitive Load on FBK Input
- Multiple Configurations - Refer to NB2304A Configurations Table
- Input Frequency Range: 15 MHz to 133 MHz
- Multiple Low-Skew Outputs
- Output-Output Skew < 200 ps
- Device-Device Skew < 500 ps
- Two Banks of Four Outputs
- Less than 200 ps Cycle-to-Cycle Jitter (-1)
- Available in Space Saving, 8 pin 150 mil SOIC Package
- 3.3 V Operation
- Advanced $0.35 \mu$ CMOS Technology
- Guaranteed Across Commercial and Industrial Temperature Ranges
- These Devices are Pb -Free, Halogen Free and are RoHS Compliant

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SOIC-8
D SUFFIX
CASE 751

MARKING DIAGRAM


| 4lx | $=$ Specific Device Code |
| :--- | :--- |
|  | x $=1$ or 2 |
| A | $=$ Assembly Location |
| L | $=$ Wafer Lot |
| Y | $=$ Year |
| W | $=$ Work Week |
| - | Pb-Free Package |

*For additional marking information, refer to Application Note AND8002/D.

## ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

## NB2304A



Figure 1. Basic Block Diagram
(see Figures 10 and 11 for device specific Block Diagrams)

Table 1. CONFIGURATIONS

| Device | Feedback From | Bank A Frequency | Bank B Frequency |
| :--- | :--- | :--- | :--- |
| NB2304AI1 | Bank A or Bank B | Reference | Reference |
| NB2304AI2 | Bank A | Reference | Reference $\div 2$ |
| NB2304AI2 | Bank B | $2 \times$ Reference | Reference |



Figure 2. Pin Configuration

Table 2. PIN DESCRIPTION

| Pin \# | Pin Name | Description |
| :---: | :---: | :--- |
| 1 | REF (Note 1) | Input reference frequency, 5 V <br> tolerant input. |
| 2 | CLKA1 (Note 2) | Buffered clock output, Bank A. |
| 3 | CLKA2 (Note 2) | Buffered clock output, Bank A. |
| 4 | GND | Ground. |
| 5 | CLKB1 (Note 2) | Buffered clock output, Bank B. |
| 6 | CLKB2 (Note 2) | Buffered clock output, Bank B. |
| 7 | V DD $^{2}$ | 3.3 V supply. |
| 8 | FBK | PLL feedback input. |

1. Weak pulldown.
2. Weak pulldown on all outputs.

## NB2304A

Table 3. MAXIMUM RATINGS

| Parameter | Min | Max | Unit |
| :--- | :---: | :---: | :---: |
| Supply Voltage to Ground Potential | -0.5 | +7.0 | V |
| DC Input Voltage (Except REF) | -0.5 | $\mathrm{~V}_{\mathrm{DD}}+0.5$ |  |
| DC Input Voltage (REF) | -0.5 | 7 | V |
| Storage Temperature | -65 | +150 | ${ }^{\circ} \mathrm{C}$ |
| Maximum Soldering Temperature (10 sec) |  | 260 | ${ }^{\circ} \mathrm{C}$ |
| Junction Temperature |  | 150 | ${ }^{\circ} \mathrm{C}$ |
| Static Discharge Voltage (per MIL-STD-883, Method 3015) |  |  |  |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. OPERATING CONDITIONS

| Parameter | Description | Min | Max | Unit |
| :---: | :--- | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{DD}}$ | Supply Voltage | 3.0 | 3.6 |  |
| $\mathrm{~T}_{\mathrm{A}}$ | Operating Temperature (Ambient Temperature) | Industrial <br> Commercial | -40 <br> 0 | 85 <br> 70 |
| $\mathrm{C}_{\mathrm{L}}$ | Load Capacitance, 15 MHz to 100 MHz |  | ${ }^{\circ} \mathrm{C}$ |  |
| $\mathrm{C}_{\mathrm{L}}$ | Load Capacitance, from 100 MHz to 133 MHz |  |  |  |
| $\mathrm{C}_{\mathrm{IN}}$ | Input Capacitance (Note 3) |  | 15 | pF |

3. Applies to both REF Clock and FBK.

Table 5. ELECTRICAL CHARACTERISTICS $\mathrm{V}_{\mathrm{CC}}=3.0 \mathrm{~V}$ to 3.6 V , $\mathrm{GND}=0 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$

| Parameter | Description | Test Conditions | Min | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {IL }}$ | Input LOW Voltage |  |  | 0.8 | V |
| $\mathrm{V}_{\mathrm{IH}}$ | Input HIGH Voltage |  | 2.0 |  | V |
| IIL | Input LOW Current | $\mathrm{V}_{\mathrm{IN}}=0 \mathrm{~V}$ |  | 50.0 | $\mu \mathrm{A}$ |
| IIH | Input HIGH Current | $\mathrm{V}_{\mathrm{IN}}=\mathrm{V}_{\mathrm{DD}}$ |  | 100.0 | $\mu \mathrm{A}$ |
| $\mathrm{V}_{\text {OL }}$ | Output LOW Voltage | $\mathrm{I}_{\mathrm{OL}}=8 \mathrm{~mA}(-1,-2)$ |  | 0.4 | V |
| $\mathrm{V}_{\mathrm{OH}}$ | Output HIGH Voltage | $\mathrm{I}_{\mathrm{OH}}=-8 \mathrm{~mA}(-1,-2)$ | 2.4 |  | V |
| IDD | Supply Current | Unloaded outputs 100 MHz REF Select inputs at $V_{D D}$ or GND |  | 45 | mA |
|  |  | Unloaded outputs, 66 MHz REF ( $-1,-2$ ) |  | 35 |  |
|  |  | Unloaded outputs, 33 MHz REF ( $-1,-2$ ) |  | 20 |  |

Table 6. SWITCHING CHARACTERISTICS $\mathrm{V}_{\mathrm{CC}}=3.0 \mathrm{~V}$ to $3.6 \mathrm{~V}, \mathrm{GND}=0 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$
(All parameters are specified with loaded outputs)

| Parameter | Description | Test Conditions | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{t}_{1}$ | Output Frequency | 30 pF load (all devices) 15 pF load ( $-1,-2$ ) | $\begin{aligned} & 15 \\ & 15 \end{aligned}$ |  | $\begin{gathered} \hline 100 \\ 133.3 \end{gathered}$ | MHz |
| $\mathrm{t}_{1}$ | Duty Cycle $=\left(\mathrm{t}_{2} / \mathrm{t}_{1}\right) * 100$ (all devices) | $\begin{aligned} & \text { Measured at } 1.4 \mathrm{~V} \text {, Fout } \leq 66.66 \mathrm{MHz} \\ & 30 \mathrm{pF} \text { load } \end{aligned}$ | 40.0 | 50.0 | 60.0 | \% |
|  |  | $\text { Measured at } 1.4 \mathrm{~V} \text {, } \mathrm{F}_{\text {Out }} \leq 50 \mathrm{MHz}$ $15 \mathrm{pF} \text { load }$ | 45.0 | 50.0 | 55.0 |  |
| $\mathrm{t}_{3}$ | Output Rise Time$(-1,-2)$ | Measured between 0.8 V and 2.0 V 30 pF load |  |  | 2.50 | ns |
|  |  | Measured between 0.8 V and 2.0 V 15 pF load |  |  | 1.50 |  |
| $\mathrm{t}_{4}$ | Output Fall Time$(-1,-2)$ | Measured between 2.0 V and 0.8 V 30 pF load |  |  | 2.50 | ns |
|  |  | Measured between 2.0 V and 0.8 V 15 pF load |  |  | 1.50 |  |
| $\mathrm{t}_{5}$ | Output-to-Output Skew on same Bank (-1, -2) | All outputs equally loaded |  |  | 200 | ps |
|  | Output Bank A-to-Output Bank B skew (-1) | All outputs equally loaded |  |  | 200 |  |
|  | Output Bank A-to-Output Bank B skew (-2) | All outputs equally loaded |  |  | 400 |  |
| $\mathrm{t}_{6}$ | Delay, REF Rising Edge to FBK Rising Edge | Measured at $\mathrm{V}_{\mathrm{DD}} / 2$ |  | 0 | $\pm 250$ | ps |
| $\mathrm{t}_{7}$ | Device-to-Device Skew | Measured at $\mathrm{V}_{\mathrm{DD}} / 2$ on the FBK pins of the device |  | 0 | 500 | ps |
| $\mathrm{t}_{J}$ | Cycle-to-Cycle Jitter$(-1)$ | Measured at 66.67 MHz , loaded outputs, 15 pF load |  |  | 180 | ps |
|  |  | Measured at 66.67 MHz , loaded outputs, 30 pF load |  |  | 200 |  |
|  |  | Measured at 133.3 MHz , loaded outputs, 15 pF load |  |  | 100 |  |
|  | Cycle-to-Cycle Jitter$(-2)$ | Measured at 66.67 MHz , loaded outputs, 30 pF load |  |  | 400 | ps |
|  |  | Measured at 66.67 MHz , loaded outputs, 15 pF load |  |  | 380 |  |
| tıock | PLL Lock Time | Stable power supply, valid clock presented on REF and FBK pins |  |  | 1.0 | ms |

## Zero Delay and Skew Control

For applications requiring zero input-output delay, all outputs must be equally loaded.


OUTPUT LOAD DIFFERENCE: FBK LOAD - CLKA/CLKB LOAD (pF)

To close the feedback loop of the NB2304A, the FBK pin can be driven from any of the four available output pins. The output driving the FBK pin will be driving a total load of 7 pF plus any additional load that it drives. The relative loading of this output (with respect to the remaining outputs) can adjust the input output delay. This is shown in Figure 3.
For applications requiring zero input-output delay, all outputs including the one providing feedback should be equally loaded. If input-output delay adjustments are required, use Figure 3 to calculate loading differences between the feedback output and remaining outputs. For zero output-output skew, be sure to load outputs equally.

Figure 3. REF Input to CLKA/CLKB Delay vs. Difference in Loading between FBK Pin and CLKA/CLKB Pins

## SWITCHING WAVEFORMS



Figure 4. Duty Cycle Timing


Figure 5. All Outputs Rise/Fall Time


Figure 6. Output - Output Skew

Figure 7. Input - Output Propagation Delay



Figure 8. Device - Device Skew

## NB2304A

## TEST CIRCUITS



Figure 9. Test Circuit \#1

## BLOCK DIAGRAMS



Figure 10. NB2304Al1


Figure 11. NB2304AI2

ORDERING INFORMATION

| Device | Marking | Operating Range | Package | Shipping $^{\dagger}$ | Availability |
| :--- | :---: | :---: | :---: | :---: | :---: |
| NB2304AI1DR2G | 411 |  <br> Commercial | SOIC-8 <br> (Pb-Free) | 2500 Tape \& Reel | Now |
| NB2304AI2DG | 412 |  <br> Commercial | SOIC-8 <br> (Pb-Free) | 98 Units / Tube | Now |
| NB2304AI2DR2G | 412 |  <br> Commercial | SOIC-8 <br> (Pb-Free) | 2500 Tape \& Reel | Now |

[^0]

SOIC-8 NB
CASE 751-07
ISSUE AK
SCALE 1:1
DATE 16 FEB 2011


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW
7. 751-01 THRU 751-06 AR
STANDARD IS 751-07.

| DIM | MILLIMETERS |  | INCHES |  |
| :---: | :---: | :---: | :---: | :---: |
|  | MIN | MAX | MIN | MAX |
|  | 4.80 | 5.00 | 0.189 | 0.197 |
| B | 3.80 | 4.00 | 0.150 | 0.157 |
| C | 1.35 | 1.75 | 0.053 | 0.069 |
| D | 0.33 | 0.51 | 0.013 | 0.020 |
| G | 1.27 BSC |  | 0.050 BSC |  |
| H | 0.10 | 0.25 | 0.004 | 0.010 |
| J | 0.19 | 0.25 | 0.007 | 0.010 |
| K | 0.40 | 1.27 | 0.016 | 0.050 |
| M | 0 | $0^{\circ}$ | $8^{\circ}$ | 0 |
|  | $\circ$ | 8 |  |  |
| N | 0.25 | 0.50 | 0.010 | 0.020 |
| S | 5.80 | 6.20 | 0.228 | 0.244 |

## GENERIC

MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
= Year
$\begin{array}{ll}\mathrm{W} & =\text { Work Week } \\ \text { - } & =\text { Pb-Free Package }\end{array}$
*This information is generic. Please refer to device data sheet for actual part marking. $\mathrm{Pb}-\mathrm{Free}$ indicator, " G " or microdot " $\mathrm{=}$ ", may or may not be present. Some products may not follow the Generic Marking.
*For additional information on our $\mathrm{Pb}-$ Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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CASE 751-07
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STYLE

| PIN 1. | EMITTER |
| ---: | :--- |
| 2. | COLLECTOR |
| 3. | COLLECTOR |
| 4. | EMITTER |
| 5. | EMITTER |
| 6. | BASE |
| 7. | BASE |
| 8. | EMITTER |
| STYLE 5: |  |
| PIN 1. | DRAIN |
| 2. | DRAIN |
| 3. | DRAIN |
| 4. | DRAIN |
| 5. | GATE |
| 6. | GATE |
| 7. | SOURCE |
| 8. | SOURCE |

STYLE 9:
PIN 1. EMITTER, COMMON
COLLECTOR, DIE \#1 COLLECTOR, DIE \#2 EMITTER, COMMON EMITTER, COMMON BASE, DIE \#2
BASE, DIE \#1
8. EMITTER, COMMON

STYLE 13:
PIN 1. N.C.
2. SOURCE
3. SOURCE

GATE
DRAIN
DRAIN
DRAIN
8. DRAIN

STYLE 17:
PIN 1. VCC
V2OUT
V10UT
V10UT
TXE
RXE
VEE
7. GND
8. ACC

STYLE 21:
PIN 1. CATHODE 1
2. CATHODE 2
3. CATHODE 3

CATHODE 4
CATHODE 5
6. COMMON ANODE
7. COMMON ANODE
8. CATHODE 6

STYLE 25:
PIN 1. VIN
2. $\mathrm{N} / \mathrm{C}$

REXT
GND
IOUT
IOUT
IOUT
8. IOUT

## STYLE 29

PIN 1. BASE, DIE \#
EMITTER, \#1
BASE, \#2
. EMITTER, \#2
5. COLLECTOR, \#2
6. COLLECTOR, \#2
7. COLLECTOR, \#1
8. COLLECTOR, \#1

STYLE
PIN 1. COLIECTOR,
2. COLLECTOR, \#
3. COLLECTOR, \#2

COLLECTOR, \#2
BASE, \#2
. EMITTER, \#2
7. BASE, \#1
8. EMITTER, \#1

STYLE 6:
PIN 1. SOURCE
DRAIN
3. DRAIN
4. SOURCE

SOURCE
6. GATE
7. GATE
8. SOURCE

STYLE 10:
PIN 1. GROUND
2. BIAS 1
3. OUTPUT

GROUND
GROUND
BIAS 2
7. INPUT
8. GROUND

STYLE 14
PIN 1. N-SOURCE
2. N-GATE
. P-SOURCE
P-GATE
5.DRAIN
6. P-DRAIN
7. N-DRAIN
8. N -DRAIN

STYLE 18
PIN 1. ANODE
2. ANODE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. CATHODE
8. CATHODE

STYLE 22 :
PIN 1. I/O LINE
2. COMMON CATHODE/VCC
3. COMMON CATHODE/VCC
4. I/O LINE 3
5. COMMON ANODE/GND
6. I/O LINE 4
7. I/O LINE 5
8. COMMON ANODE/GND

STYLE 26:
PIN 1. GND
2. $\mathrm{dv} / \mathrm{dt}$
3. ENABLE
4. ILIMIT

SOURCE
SOURCE
SOURCE
8. VCC

STYLE 30:
PIN 1. DRAIN 1
2. DRAIN 1
. GATE 2
4. SOURCE 2
5. SOURCE 1/DRAIN 2
. SOURCE 1/DRAIN 2
SOURCE 1/DRAIN 2
8. GATE 1

STYLE 3
STYLE
2. DRAIN, DIE
2. DRAIN, \#1
2. DRAIN, \#
3. DRAIN, \#2
4. DRAIN, \#2
5. GATE, \#2
7. GATE, \#1
8. SOURCE, \#1

## STYLE 7

PIN 1. INPUT
2. EXTERNAL BYPASS
3. THIRD STAGE SOURCE
4. GROUND
5. DRAIN
6. GATE 3
7. SECOND STAGE Vd
8. FIRST STAGE Vd

## STYLE 11:

PIN 1. SOURCE
2. GATE 1
3. SOURCE 2
4. GATE 2
5. DRAIN 2
6. DRAIN 2
7. DRAIN 1
8. DRAIN 1

## STYLE 15:

PIN 1. ANODE 1
2. ANODE 1
3. ANODE 1
4. ANODE 1
5. CATHODE, COMMON
6. CATHODE, COMMON
7. CATHODE, COMMON
8. CATHODE, COMMON

## STYLE 19:

PIN 1. SOURCE
2. GATE 1
3. SOURCE 2
4. GATE 2
5. DRAIN
6. MIRROR 2
7. DRAIN 1
8. MIRROR 1

## STYLE 23:

PIN 1. LINE 1 IN
2. COMMON ANODE/GND
3. COMMON ANODE/GND
4. LINE 2 IN
5. LINE 2 OUT
6. COMMON ANODE/GND
7. COMMON ANODE/GND
8. LINE 1 OUT

STYLE 27:
PIN 1. ILIMIT
2. OVLO
3. UVLO
4. INPUT+
5. INPUT+
5. SOURCE
6. SOURCE
7. SOURCE
8. DRAIN

STYLE 4:
PIN 1. ANODE
2. ANODE
3. ANODE
4. ANODE
5. ANODE
6. ANODE
8. COMMON CATHODE

## STYLE 8:

PIN 1. COLLECTOR, DIE \#1
2. BASE, \#1
3. BASE, \#2
4. COLLECTOR, \#2
5. COLLECTOR, \#2
6. EMITTER, \#2
7. EMITTER, \#1
8. COLLECTOR, \#1

## STYLE 12

PIN 1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

## STYLE 16:

PIN 1. EMITTER, DIE \#1
2. BASE, DIE \#1
3. EMITTER, DIE \#2
3. EMITTER, DIE
4. BASE, DIE \#2
4. BASE, DIE \#2
6. COLLECTOR, DIE \#2
7. COLLECTOR, DIE \#1
8. COLLECTOR, DIE \#1

## STYLE 20:

PIN 1. SOURCE (N)
2. GATE (N)
3. SOURCE (P)
4. GATE (P)
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

STYLE 24
PIN 1. BASE
2. EMITTER
3. COLLECTOR/ANODE
4. COLLECTOR/ANODE
5. CATHODE
6. CATHODE
7. COLLECTOR/ANODE
8. COLLECTOR/ANODE

## STYLE 28:

PIN 1. SW_TO_GND
2. DASIC $\bar{O} F F$
3. DASIC_SW_DET
4. GND
5. V_MON
6. VBULK
7. VBULK
8. VIN

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LMX2430TMX/NOPB NB3N5573DTG ADF4153ABCPZ PI6C2405A-1LE CD74HC4046AM CPLL66-2450-2450 NJM567D
74HC4046ADB. 112 74HC4046APW. 112 CY23S05SXI-1 STW81200T ADF4208BRUZ ADF4218LBRUZ ADF4355-3BCPZ ADF4355-
2BCPZ ADF4355BCPZ ADF4169WCCPZ ADF4360-7BCPZ ADF4360-6BCPZ ADF4360-5BCPZRL7 ADF4360-5BCPZ ADF43604BCPZRL7 ADF4360-4BCPZ ADF4360-3BCPZ ADF4360-2BCPZRL7 ADF4252BCPZ ADF4159CCPZ ADF4169CCPZ ADF4252BCPZR7 ADF4360-0BCPZ ADF4360-1BCPZ ADF4360-1BCPZRL7 ADF4360-2BCPZ ADF4360-3BCPZRL7 ADF4360-7BCPZRL7 ADF43608BCPZ ADF4360-8BCPZRL7 ADF4360-9BCPZ ADF4360-9BCPZRL7 ADF4159CCPZ-RL7 ADF4159WCCPZ ADF4360-0BCPZRL7

AD9901KPZ AD9901KQ


[^0]:    $\dagger$ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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